

ABSTRACT OF THE DISCLOSURESEMICONDUCTOR CHIP AND SEMICONDUCTOR PACKAGE

5 The driver semiconductor package includes a base
substrate. The semiconductor package includes a
semiconductor chip mounted on the base substrate. The
semiconductor chip includes a core region disposed in a center
part of the semiconductor chip, an internal circuit being
10 provided in the core region. The semiconductor chip includes a
plurality of IO cell regions disposed in a line along a side of the
semiconductor chip, a differential circuit being provided in each
of the plurality of IO cell regions. The semiconductor chip
includes a non-inverting pad electrode disposed above each of
15 the IO cell regions and electrically connected to a non-inverting
terminal of the differential circuit. The semiconductor chip
includes an inverting pad electrode disposed above each of the
IO cell regions and connected to an inverting terminal of the
differential circuit.

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Fig. 1